

ABSTRACT OF THE DISCLOSURE

An acute tip is formed on each top of bump electrodes of a semiconductor device to be mounted on a printed circuit board by facedown bonding. Each acute tip is then applied a leveling process as to form a small flat surface on its top. After that, each of the bump electrode is depressed gradually with heat for transforming the bump electrode against a conductor pattern of the printed circuit board for mounting. Resultantly, the semiconductor device is mounted on the printed circuit board firmly and without including foreign body between the bump electrode of the semiconductor device and the conductor pattern of the printed circuit board.

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